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Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

5 1-10 (cancelled).

11 (currently amended): A chip-packaging with bonding options connected to a package substrate, comprising:

the package substrate connected to either a high voltage or a low voltage;

10 a chip mounted on the package substrate, the chip comprising a plurality of bonding option units, each bonding option unit comprising a bonding pad; and

15 a plurality of first lead frames, ~~each~~ the bonding pad of each bonding option unit ~~the chip~~ having a corresponding first lead frame, the first lead frames being connected to either a high voltage or a low voltage, wherein the voltage level of the first lead frames is the logical opposite of the voltage level of the package substrate;

20 wherein ~~each~~ the bonding pad of each bonding option unit is selectively connected to the package substrate or the corresponding first lead frame for providing ~~an appropriate voltage to the corresponding bonding option unit~~ two types of bonding options for each bonding option unit.

25 12-18 (cancelled).

19 (currently amended): A method of packaging a chip having a bonding option connected to a package substrate, comprising:

providing the package substrate;

connecting the package substrate to either a high voltage or a low voltage;

30 mounting the chip on the package substrate, the chip comprising a plurality of bonding option units, each bonding option unit comprising a

bonding pad;

providing a plurality of first lead frames, each the bonding pad of each
bonding option unit ~~the chip~~ having a corresponding first lead frame,
the first lead frames being connected to either a high voltage or a low
voltage, wherein the voltage level of the first lead frames is the logical
opposite of the voltage level of the package substrate; and
connecting each the bonding pad of each bonding option unit to the package
substrate or the corresponding first lead frame for providing an-
~~appropriate voltage to the corresponding bonding option unit~~ two types
of bonding options for each bonding option unit.

20-32 (cancelled).

33 (currently amended): The chip-packaging of claim 11, further comprising a
plurality of second lead frames, each bonding pad of the chip having a
corresponding second lead frame, wherein the second lead frames are used
for inputting or outputting signals to the corresponding bonding pad, and
each bonding pad is ~~selectively~~ connected to the package substrate, the
corresponding first lead frame, or the corresponding second lead frame for
providing three types of bonding options for each bonding option unit.

34 (currently amended): The method of claim 19, further comprising providing a
plurality of second lead frames, each bonding pad of the chip having a
corresponding second lead frame, wherein the second lead frames are used
for inputting or outputting signals to the corresponding bonding pad, and
each bonding pad is ~~selectively~~ connected to the package substrate, the
corresponding first lead frame, or the corresponding second lead frame for
providing three types of bonding options for each bonding option unit.